

02-13-2009



103548165

To the Director of the U.S. Patent and

documents or the new address(es) below.

1. Name of conveying party(ies)/Execution Date(s).

MASATOSHI FUJINO (01/19/2009),
MASAYOSHI KOGANEI (01/19/2009),
YUTAKA OGASAWARA (01/19/2009),

Name of receiving party(ies)

Name: SONY CORPORATION

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Street Address: _____

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108-0075
JAPAN

City: _____

State: _____

Country: _____ Zip: _____

Additional name(s) & address(es) attached? Yes No

Execution Date(s): in parentheses after inventor name

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of Conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other _____

4. Application or patent number(s):

A. Patent Application No.(s)

This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Dennis M. Smid, Esq.
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6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
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b. Deposit Account Number 12-1095
Authorized User Name Dennis M. Smid, Esq.

9. Signature:

Signature

Dennis M. Smid, Esq. - 34,930

Name of Person Signing

02/12/2009 DBYRNE 0000004 121095 12322439

01 FC:8021 February 3, 2009
Date

Total number of pages including cover sheet, attachments, and documents:

5

Additional Conveying Party(ies)/Execution Date(s) (1. Continued):

YASUSHI ITOSHIRO (01/19/2009), KAZUHITO SATO (01/19/2009), AND KAZUHIKO OTAKE (01/19/2009)

Additional Assignees (2. Continued):

Assignee Name: _____

Internal Address: _____

Street Address: _____

City: _____ State: _____ Country: _____ Zip: _____

Assignee Name: _____

Internal Address: _____

Street Address: _____

City: _____ State: _____ Country: _____ Zip: _____

Assignee Name: _____

Internal Address: _____

Street Address: _____

City: _____ State: _____ Country: _____ Zip: _____

Additional Applications and/or Patents (4. Continued):

Additional Patent Application Numbers
4A. Continued:

Additional Patent Numbers
4B. Continued:

Additional numbers attached?

Yes

No

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in KEYBOARD AND ELECTRONIC EQUIPMENT

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all prior rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date in this application in the spaces that follow: Serial Number: _____, Filing Date: _____

This assignment executed on the dates indicated below.

<u>Masatoshi FUJINO</u> Name of first or sole inventor	<u>January 19, 2009</u> Execution date of U.S. Patent Application
<u>Tokyo, Japan</u> Residence of first or sole inventor	
<u>Masatoshi Fujino</u> Signature of first or sole inventor	<u>January 19, 2009</u> Date of this assignment

Masayoshi KOGANEI
Name of second inventor

January 19, 2009
~~January 20, 2009~~
Execution date of U.S. Patent Application

Tokyo, Japan
Residence of second inventor

January 19, 2009
~~January 20, 2009~~
Date of this assignment

Masayoshi Koganei
Signature of second inventor

January 19, 2009

Yutaka OGASAWARA
Name of third inventor

January 19, 2009
Execution date of U.S. Patent Application

Saitama, Japan
Residence of third inventor

January 19, 2009
Date of this assignment

Yutaka Ogasawara
Signature of third inventor

Yasushi ITOSHIRO
Name of fourth inventor

January 19, 2009
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Residence of fourth inventor

January 19, 2009
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Yasushi Itoshiro
Signature of fourth inventor

Kazuhito SATO
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January 19, 2009
Execution date of U.S. Patent Application

Tokyo, Japan
Residence of fifth inventor

January 19, 2009
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Kazuhito Sato
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Kazuhiko OTAKE
Name of sixth inventor

January, 19, 2009
Execution date of U.S. Patent Application

Tokyo, Japan
Residence of sixth inventor

Kazuhiko Otake
Signature of sixth inventor

January, 19, 2009
Date of this assignment

Name of seventh inventor

Execution date of U.S. Patent Application

Residence of seventh inventor

Signature of seventh inventor

Date of this assignment

Name of eighth inventor

Execution date of U.S. Patent Application

Residence of eighth inventor

Signature of eighth inventor

Date of this assignment

Name of ninth inventor

Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor

Date of this assignment

PATENT